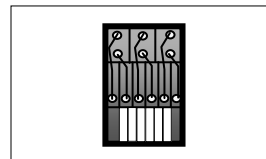


Earl J. Lum  
+1-650-430-2221  
[elum@ejlwireless.com](mailto:elum@ejlwireless.com)



## Nokia GSM/UMTS/LTE Flexi MultiRadio 10 Baseband Capacity Expansion Unit

Model FBBC

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